

Through hole plating process for hybrid circuits

Patent number: FR2714567
Publication date: 1995-06-30
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Classification:
- international: H05K3/42
- european: H05K3/00R; H05K3/40D2
Application number: FR19930015739 19931228
Priority number(s): FR19930015739 19931228

Abstract of **FR2714567**

The through-hole plating process is for metallising a through hole in a hybrid circuit substrate (S), which is placed on a position and maintenance tool (20), with an intermediate filter layer (21). Ink is passed from a container (14) and through a nozzle to a positioned mask (12) and then to the substrate hole. Ink is sucked through the hole by a pump (17) and the special cellulose nitrate intermediate filter with 8 microns porosity controls the flow, thus providing even metallisation around the edges.

2 family member for:

FR2714567

Derived from 1 application.

1 Through hole plating process for hybrid circuits

Publication info: **FR2714567 A1** - 1995-06-30

FR2714567 B1 - 1996-01-26